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III. AMENDMENTS TO THE CLAIMS

MARKED VERSION OF CLAIMS WITH PRESENT STATUS DELINEATED

- THE CLAIMS ARE HEREIN AMENDED, CANCELLED, OR ADDED TO, SO AS TO EVENTUATE IN THE NEW SET OF PENDING CLAIMS INDICATED BELOW. THIS LISTING OF CLAIMS WILL REPLACE ALL PRIOR VERSIONS AND LISTING OF CLAIMS IN THE APPLICATION.

-- The status of each claim is indicated after the claim number by use of a parenthetical identifier selected from: (Original), (Currently amended), (Canceled), (Withdrawn), (Withdrawn – currently amended), (Previously presented), (New), and (Not entered). Claim text is provided for each claim in the listing except for the claims status “canceled” or “not entered.” Only claims having the status of “Currently amended” or “Withdrawn – currently amended” include markings to indicate changes that have been made relative to the immediate prior version of the claims. The text of any deleted matter is shown by strike-through, except that double brackets, placed before and after deleted characters of five or fewer consecutive characters, may be used. The text of any added subject matter is shown by underlining the added text. Claims that were previously canceled that are reinstated here, if any, are reinstated by adding the claim as a “(New)” claim with a new claim number.

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WHAT IS CLAIMED IS:

1. - 20. (Canceled)

21. (New) A method for forming a low-gluten wafer consisting of only wheat, said method comprising the steps of:

- a. mixing about 1 part wheat starch with about 1 part pre-gelatinized wheat starch to form an homogenous starch mixture;
- b. adding water to said starch mixture in a weight ratio of about 1 part water to about 1 part said homogenous starch mixture;
- c. mixing the water into said starch mixture to form a water-starch mixture;
- d. placing said water-starch mixture between two plates each heated to about 275 - 400 degrees Fahrenheit;
- e. heating for between about 5 minutes to about 10 minutes; and
- f. removing said wafers from between said two plates.

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